

REMARKS

By the present amendment, claims 1 through 3 have been amended to obviate the examiner's objections thereto and/or to further clarify the concepts of the present invention. Entry of these amendments is respectfully requested.

In the Office Action, claims 1-3 were rejected under 35 USC § 102(b) as being anticipated by the cited '511 Japanese patent publication. In making this rejection, the position was that the cited publication teaches a solid electrolytic capacitor as claimed where the cathode terminal has two portions in the same plane which are exposed from an enclosure. Reconsideration of this rejection in view of the above claim amendments and the following comments is respectfully requested.

Before discussing the rejection in detail, a brief review of the presently claimed invention may be quite instructive. The solid electrolytic capacitor of the presently claimed invention includes, among other things, one cathode terminal where the cathode terminal is exposed from the enclosure resin in two locations on the same plane. This structure allows the solid electrolytic capacitor to be securely soldered to a circuit board. It is submitted that such a solid electrolytic capacitor is not taught or suggested by the cited '511 Japanese patent publication.

More particularly, the solid electrolytic capacitor disclosed in the '511 Japanese patent publication includes one cathode terminal, and this cathode terminal is exposed from the enclosure resin in two or four locations outside of a portion where the anode terminal is exposed from the enclosure resin. This structure allegedly allows the capacitor to be mounted in positive direction even if the direction is changed by 180°.

While the solid electrolytic capacitor of the presently invention has one cathode terminal as does the solid electrolytic capacitor disclosed in the '511 Japanese patent publication, the cathode terminal is bent according to the '511 Japanese patent publication. On the other hand, the cathode terminal is not bent in the presently claimed invention. Since the cathode terminal of the presently claimed invention is in direct contact with a circuit board, the cathode terminal does not need to be bent.

As a consequence of this structure according to the invention, a current path from the capacitor element to the circuit board can be shortened to thereby reduce the ESR and the ESL in the solid electrolytic capacitor finished product as is set forth on page 2, line 20 to page 3, line 1 of the subject specification. In distinct contrast, in the solid electrolytic capacitor disclosed in the '511 Japanese patent publication, the cathode terminal is bent as is shown in FIG. 1 and FIG. 2 thereof. As a consequence, a current path in this electrolytic capacitor from the capacitor element to a circuit board is quite long and therefore the ESL and ESR cannot be reduced.

To clarify these significant differences between the electrolytic capacitor of the presently claimed invention and that of the '511 Japanese patent publication, claim 1 has been amended to recite that the platy cathode terminal mounting the capacitor element thereon is "connected with the cathode layer on an upper face thereof." In addition, claim 1 has been amended to recite that a part of a lower face of the platy cathode terminal is "exposed on a same plane from the enclosure resin."

It is apparent from FIG. 1 of the subject application that the cathode terminal mounts the capacitor element and is connected with the cathode layer on an upper face, and that the lower face of the platy cathode terminal is exposed from the enclosure resin. Thus, the subject specification supports the claim amendments in claim 1 directed to the solid electrolytic capacitor where the cathode exposed portion comprises a first cathode exposed portion and a second cathode exposed portion, and a cathode buried portion having the enclosure resin buried therein is provided between the first cathode exposed portion and the second cathode exposed portion. With respect to the recitation in claim 1 that the enclosure resin is buried between the first cathode exposed portion and the second cathode exposed portion, such is described on page 7, line 21 to page 8, line 1 of the subject specification.

This structure of a solid electrolytic capacitor enables the capacitor to be fixed at three points, that is, the anode exposed portion, the first cathode exposed portion, and the

second cathode exposed portion. Therefore, the solid electrolytic capacitor can be securely soldered while maintaining the ESL reduction effect as is set forth on page 10, lines 6-13 of the subject specification.

It is further submitted that the '511 patent publication does not teach or suggest the subject matter of amended dependent claim 2. More particularly, this claim recites that the first exposed portion is in a closer location to the anode exposed portion than the second exposed portion is. In this electrolytic capacitor, a distance between current paths of each of an anode and a cathode to an external circuit board can be shortened, so that the ESL in a high-frequency area can be further reduced as is set forth on page 3, lines 2-7 of the subject specification. In distinct contrast, the solid electrolytic capacitor shown in FIG. 1 and FIG.2 of the '511 Japanese patent publication has the distances between each of positions where the cathode terminal is exposed from the enclosure resin and a position where the anode terminal is exposed from the enclosure resin which are equal.

It is further submitted that the '511 patent publication does not teach or suggest the subject matter of dependent claim 3. More specifically, this claim recites that the first exposed portion extends to end portions of the solid electrolytic capacitor in a transverse direction on the same plane. With this structure for an electrolytic capacitor, solder paste can be checked at a glance from the side face after a process therefor as is set forth on page 10, lines 14-18 of the subject specification.

On the other hand, the solid electrolytic capacitor disclosed in the '511 Japanese patent publication has solder paste on the portion where the anode terminal is exposed from the enclosure resin which cannot be checked. This is because the cathode terminal is exposed from the enclosure resin at the outside of the portion where the anode terminal is exposed from the enclosure resin.

For the reasons stated above, withdrawal of the rejection under 35 U.S.C. § 102(b) and allowance of claims 1 through 3 as amended over the cited '511 Japanese patent publication are respectfully requested.

Dependent claim 4 was rejected under 35 USC § 103(a) as being unpatentable over the same '511 Japanese patent publication in view of the '841 Japanese patent publication. In making this rejection, it was acknowledged that the former patent publication does not teach a method of soldering a solid electrolytic capacitor to the lands of a circuit board. It then was asserted that the '841 Japanese patent publication supplies these teaching deficiencies. Reconsideration of this rejection in view of the above claim amendments and the following comments is respectfully requested.

The above remarks relative to the teaching deficiencies of the '511 Japanese patent publication relative to independent claim 1 are reiterated here with regard to this rejection. It is submitted that the '841 Japanese patent publication does not supply these teaching

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deficiencies. Accordingly, withdrawal of the rejection under 35 U.S.C. § 103(a) and allowance of claim 4 over the cited patent publications are respectfully requested.

In view of the foregoing, it is submitted that the subject application is now in condition for allowance and early notice to that effect is earnestly solicited.

In the event this paper is not timely filed, the undersigned hereby petitions for an appropriate extension of time. The fee for this extension may be charged to Deposit Account No. 01-2340, along with any other additional fees which may be required with respect to this paper.

Respectfully submitted,

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